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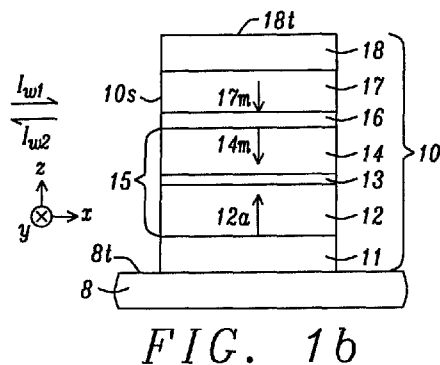
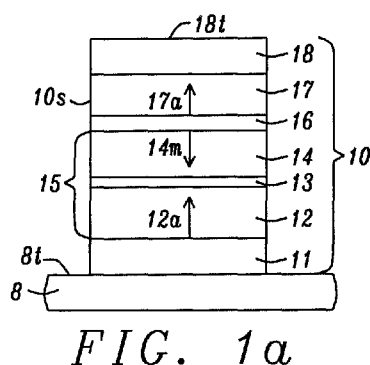
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(54) Title: INITIALIZATION PROCESS FOR MAGNETIC RANDOM ACCESS MEMORY (MRAM) PRODUCTION



(57) **Abstract:** An initialization process is disclosed for a perpendicular magnetic tunnel junction (p-MTJ) wherein the switching error rate is reduced from a typical range of 30-100 ppm to less than 10 ppm. In one embodiment, an in-plane magnetic field is applied after a final anneal step is performed during memory device fabrication such that all magnetizations in the free layer, and AP1 and AP2 pinned layers are temporarily aligned "in-plane". After the applied field is removed, interfacial perpendicular magnetic anisotropy (PMA) at a tunnel barrier/API interface induces a single AP1 magnetic domain with a magnetization in a first vertical direction. Interfacial PMA at a FL/tunnel barrier interface affords a single FL domain with magnetization in the first direction or opposite thereto. AP2 magnetization is opposite to the first direction as a result of antiferromagnetic coupling with the AP1 layer. Alternatively, a perpendicular- to-plane magnetic field may be applied for initialization.

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
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INITIALIZATION PROCESS FOR MAGNETIC RANDOM ACCESS MEMORY (MRAM) PRODUCTION

RELATED PATENT APPLICATIONS

This application is related to Docket # HT17-011, serial number 15/668,113, filed on 8/3/17; and HT17-038, serial number 16/056791, filed 8/7/18; which are assigned to a common assignee and herein incorporated by reference in their entirety.

TECHNICAL FIELD

The present disclosure relates to a method of establishing a single domain in the pinned layer of a magnetic tunnel junction (MTJ) thereby providing a lower switching error rate of an adjacent free layer during a write process, and leading to lower power consumption with longer device lifetimes.

BACKGROUND

Perpendicularly magnetized magnetic tunnel junctions (p-MTJs) are a major emerging technology for use in embedded MRAM applications, in standalone MRAM applications, and in spin-torque transfer (STT)-MRAM. STT-MRAM is a p-MTJ technology using spin-torque for writing of memory bits that was described by C. Slonezewski in "Current driven excitation of magnetic multilayers", J. Magn. Magn. Mater. V 159, L1-L7 (1996). P-MTJ technologies that have a high operating speed, low power consumption, excellent endurance, non-volatility, and scalability are highly competitive with existing semiconductor memory technologies such as SRAM, DRAM, and flash.

MRAM and STT-MRAM employ a p-MTJ cell as a switching and storage device. P-MTJs have a general structure wherein an insulating tunnel barrier layer is sandwiched between two magnetic layers. One of the magnetic layers is called the pinned layer and has a magnetization fixed in an out-of-plane direction in the (+z) direction, for example, when the plane of the magnetic layer

is formed along the x-axis and y-axis directions. The pinned layer may have a synthetic antiparallel (SyAP) configuration in which an inner magnetic (AP1) layer adjoining the tunnel barrier layer is antiferromagnetically coupled with an outer magnetic (AP2) layer through an intermediate antiferromagnetic coupling (AFC) layer such as Ru. The second magnetic layer called the free layer also has an out-of-plane magnetization with a direction that is free to be either parallel in a (+z) direction (P state) or anti-parallel in a (-z) direction (AP state) to that of the AP1 layer. The difference in resistance between the P state (R_P) and AP state (R_{AP}) can be characterized by the equation $(R_{AP}-R_P)/R_P$ that is also known as DRR or the magnetoresistive (MR) ratio. It is important for p-MTJ devices to have a large DRR value since this property is directly related to the read margin for the memory bit, or the ease of differentiating between the P state and AP state (0 or 1 bits).

The stability of the magnetizations for the AP1 and AP2 pinned layers is very important for optimum p-MTJ performance in that the antiparallel alignment of the two layers provides the proper spin current for magnetization switching of the free layer during a write process. Ideally, a single domain is formed in both of the AP1 and AP2 layers. However, as a result of the MRAM fabrication process, multiple domains generally form in both pinned layers. Accordingly, spin current during a write process is often weak and insufficient to switch the free layer magnetization.

In order for p-MTJs to be more competitive with competing memory technologies, write performance must be significantly improved while maintaining the other critical device properties such as DRR. Since STT-MRAM is typically embedded in Complementary Metal Oxide Semiconductor (CMOS) devices, the pinned layer and free layer magnetizations must withstand thermal processing up to 400°C temperatures.

SUMMARY

One objective of the present disclosure is to provide an initialization process to eliminate multiple domains in a pinned layer in a p-MTJ cell such that the current needed to switch free layer magnetization is more uniform and

minimized across a plurality of p-MTJ cells in memory devices including MRAM and STT-MRAM, and in other spintronic devices.

A second objective of the present disclosure is to perform the initialization process according to the first objective such that the error rate for switching free layer magnetization is less than 10 ppm.

According to preferred embodiments, these objectives are achieved with a single initialization step wherein a magnetic field is applied to a p-MTJ stack of layers in an in-plane (horizontal) direction, or in a perpendicular-to-plane (vertical) direction. The p-MTJ stack of layers may be in the form of a plurality of p-MTJ cells each having an uppermost capping layer, and a sidewall that stops on a substrate such as a bottom electrode. The p-MTJ stack has at least a pinned layer and free layer (FL), and a tunnel barrier between the FL and pinned layer. In preferred embodiments, the pinned layer has a synthetic antiparallel (SyAP) configuration wherein an inner pinned (AP1) layer adjoins the tunnel barrier layer, and is antiferromagnetically (AF) coupled to an outer pinned (AP2) layer through an intermediate AF coupling (AFC) layer such as Ru.

In a bottom spin valve embodiment, the SyAP pinned layer is below the tunnel barrier and FL. There is also a top spin valve embodiment for the p-MTJ where the SyAP pinned layer is above the tunnel barrier and FL. The present disclosure also encompasses a dual spin valve structure where a first SyAP pinned layer is formed below a first non-magnetic spacer (SP1), a second SyAP pinned layer is formed above a second non-magnetic spacer (SP2), and the FL is between SP1 and SP2. Each of SP1 and SP2 may be a tunnel barrier, or a composite layer with conductive metal pathways in a dielectric matrix.

In a first embodiment where the applied magnetic field for initialization is “in-plane” and parallel to the planes of the p-MTJ layers, the field has sufficient magnitude to align all AP1 and AP2 magnetic domains in a horizontal direction. After the applied field is removed, the tunnel barrier/AP1 interface induces interfacial perpendicular magnetic anisotropy (PMA) such that all AP1 domains have a magnetization in a vertical direction. Because of AF coupling, all domains in the AP2 layer are aligned antiparallel to the AP1 domains. Effectively, each of the AP1 and AP2 layers has a single domain aligned in a vertical direction.

According to a second embodiment, the initialization process is accomplished with an applied magnetic field in the vertical direction. The applied field causes magnetizations in all regions of the AP1 and AP2 layers to be aligned in the direction of the applied field. Once the applied field is removed, AF coupling through the AFC layer causes magnetizations in all regions of the AP1 layer to be aligned antiparallel to the vertical magnetizations in the AP2 layer, and each of the AP1 and AP2 layers effectively has a single domain.

In some embodiments, the initialization step is performed after a final annealing step after the MTJ cell has been patterned. Moreover, the initialization step may occur before, during, or after depositing an encapsulation layer to electrically insulate p-MTJ cells from one another. In other embodiments, the initialization step may be performed a plurality of times, and the final initialization step occurs after the final anneal.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1a and FIG. 1b are cross-sectional views of a p-MTJ wherein a free layer (FL) magnetization is aligned antiparallel and parallel, respectively, to an AP1 pinned layer magnetization in a bottom spin valve configuration according to an embodiment of the present disclosure.

FIG. 2a and FIG. 2b are cross-sectional views of a p-MTJ wherein a FL magnetization is aligned antiparallel and parallel, respectively, to an AP1 pinned layer magnetization in a top spin valve configuration according to an embodiment of the present disclosure.

FIG. 3a and FIG. 3b are cross-sectional views of a dual magnetic tunnel junction (DMTJ) wherein a FL magnetization is aligned antiparallel and parallel, respectively, to two AP1 layer magnetizations to give AP/AP and P/P magnetic states according to an embodiment of the present disclosure.

FIG. 3c and FIG. 3d are cross-sectional views of a DMTJ wherein a FL magnetization is aligned parallel to one AP1 layer magnetization and antiparallel to the other AP1 layer magnetization to give P/AP and AP/P magnetic states according to an embodiment of the present disclosure.

FIG. 4 is a cross-sectional view of a portion of a p-MTJ wherein multiple magnetic domains are formed in the free layer, and in the AP1 and AP2 pinned layers as a result of annealing or stray magnetic fields.

FIG. 5 is a cross-sectional view of the p-MTJ in FIG. 4 during an initialization process comprising application of a horizontal magnetic field according to a first embodiment of the present disclosure.

FIGS. 6a-6b are cross-sectional views showing equal probabilities of magnetizations in the p-MTJ layers in FIG. 5 after the applied magnetic field is removed and interfacial PMA generates vertical magnetic domains in the free layer and AP1 layer, and AF coupling is responsible for AP2 magnetization antiparallel to AP1 magnetization according to an embodiment of the present disclosure.

FIG. 7 is a cross-sectional view of the p-MTJ in FIG. 4 during an initialization process comprising application of a vertical magnetic field according to a second embodiment of the present disclosure.

FIG. 8 is a cross-sectional view of showing magnetizations in the p-MTJ layers in FIG. 7 after the vertical magnetic field is removed, and AF coupling is responsible for AP2 magnetization that is antiparallel to AP1 magnetization according to an embodiment of the present disclosure.

FIG. 9 is a top-down view of an array of p-MTJ cells that are insulated by an encapsulation layer and formed according to an embodiment of the present disclosure.

FIG. 10 is a plot of the difference in measured current for parallel (P) and antiparallel (AP) states as a function of the P state switching current for p-MTJ cells that have not been subjected to an initialization process of the present disclosure.

FIG. 11 is a plot of the difference in measured current for parallel (P) and antiparallel (AP) states as a function of the P state switching current for p-MTJ cells that were subjected to an initialization process of the present disclosure.

DETAILED DESCRIPTION

The present disclosure is an initialization step comprising the application of a magnetic field to temporarily set all magnetic domains in the free layer (FL), AP1 pinned layer, and AP2 pinned layer in a first direction that is either in the planes of the p-MTJ layers or orthogonal to the planes of the p-MTJ layers. After the applied field is removed, interfacial perpendicular anisotropy (PMA) that results from metal oxide/ferromagnetic layer interfaces at the AP1/tunnel barrier and tunnel barrier/FL boundaries induces PMA character in the AP1 and FL layers. AF coupling through an AFC layer is responsible for establishing AP2 magnetization that is antiparallel to that of AP1. Although only one p-MTJ cell is depicted in the drawings with cross-sectional views, one skilled in the art appreciates that a plurality of p-MTJ cells is formed in an array of rows and columns in a typical memory device pattern. The planes of the p-MTJ layers are laid out along the x-axis and y-axis directions, and a thickness of each layer is in the z-axis direction. The initialization step described herein is advantageously used to lower the switching current, and lower the switching error rate during a write process in a memory device such as MRAM, STT-MRAM, or in spintronic devices including but not limited to a spin torque oscillator (STO), sensors, and biosensors.

Referring to FIG. 1a, the present disclosure encompasses a p-MTJ **10** having a sidewall **10s** that stops on top surface **8t** of substrate **8**. The p-MTJ has a bottom spin valve configuration wherein an optional seed layer **11**, pinned layer **15**, non-magnetic spacer **16**, FL **17**, and capping layer **18** with top surface **18t** are sequentially formed on the substrate that in some embodiments is a bottom electrode (BE). The bottom electrode may be a multilayer structure and is typically embedded in a dielectric layer (not shown). Preferably, the pinned layer has a SyAP configuration wherein the inner AP1 layer **14** contacts a bottom surface of the tunnel barrier, the outer AP2 layer **12** adjoins a top surface of the seed layer, or the bottom electrode in other embodiments, and AFC layer **13** is between the AP1 and AP2 layers. The present disclosure also anticipates that at least one additional layer may be included in the aforementioned MTJ stack such as a metal oxide Hk enhancing layer (not

shown) between the FL and capping layer that enhances PMA in the FL by introducing an additional FL/metal oxide interface.

In the exemplary embodiment, FL **17** has magnetization **17a**, which is aligned in a positive z-axis direction, AP1 layer **14** has magnetization **14m** aligned in a negative z-axis direction towards BE top surface **8t**, and AP2 layer has magnetization **12a** that is antiparallel to **14m**. Alternatively, all of the aforementioned magnetizations could be flipped 180° (not shown) to effectively yield the same AP state depicted in FIG. 1a.

A write process that comprises switching current **lw1** may be employed to switch the AP state in p-MTJ **10** in FIG. 1a to the P state in FIG. 1b. Magnetizations **14m**, **12a** for the AP1 and AP2 layers, respectively, remain unchanged in the p-MTJ. However, FL magnetization **17m** is now aligned parallel to **14m** in the p-MTJ shown in FIG. 1b. Switching current **lw2** is used to switch the P state of p-MTJ **10** in FIG. 1b to the AP state in FIG. 1a. Those skilled in the art will appreciate that one or more p-MTJ cells in the memory array may be selectively switched from the P state to AP state, or vice versa during a write process.

In all of the embodiments disclosed herein, seed layer **11** may be comprised of one or more of NiCr, Ta, Ru, Ti, TaN, Cu, Mg, or other elements or alloys typically employed to promote a smooth and uniform grain structure in overlying p-MTJ layers. Within SyAP layer **15**, the AFC layer **13** is preferably Ru with a thickness of 4, 9, or 14 Angstroms to provide optimal AF coupling between AP1 layer **14** and AP2 layer **12**. Optionally, Rh or Ir may serve as the AFC layer. Each of the AP1 and AP2 layers may be comprised of one or more of Co, Fe, and Ni, or an alloy thereof with B. In other embodiments, one or both of the AP1 and AP2 layers may be a laminated stack with inherent PMA such as (Co/Ni)_n, (CoFe/Ni)_n, (Co/NiFe)_n, (Co/Pt)_n, (Co/Pd)_n, or the like where n is the lamination number. Furthermore, a transitional layer such as CoFeB may be inserted between the uppermost layer in the laminated stack and tunnel barrier layer **16** to provide a CoFeB interface with the tunnel barrier thereby enhancing DRR for MTJ **10**.

According to one preferred embodiment, non-magnetic spacer **16** is a tunnel barrier layer having a metal oxide composition that is one of MgO, TiOx, AlTiO, MgZnO, Al₂O₃, ZnO, ZrOx, HfOx, or MgTaO. More preferably, MgO is selected as the tunnel barrier layer because MgO provides the highest magnetoresistive

ratio (DRR), especially when sandwiched between two CoFeB layers, for example. In other embodiments, the non-magnetic spacer may be a so-called CCP layer wherein conducting current paths made of a metal are formed in a metal oxide matrix.

Free layer **17** may be comprised of the same material as in AP1 layer **14**, or in AP2 layer **12**. In another embodiment, the FL may have a non-magnetic moment diluting layer such as Ta or Mg that is inserted between two ferromagnetically coupled CoFe or CoFeB layers. Moreover, the FL may have a SyAP configuration such as FL1/Ru/FL2 where FL1 and FL2 are first and second ferromagnetic (FM) layers that are antiferromagnetically coupled.

Capping layer **18** serves as a hard mask during patterning and planarization processes that are employed to form p-MTJ **10**, and is typically comprised of one or more of Ta, Ru, TaN, Ti, TiN, and W, or the like. All p-MTJ layers may be deposited with a DC sputter deposition process that generally comprises argon sputter gas and a base pressure between 5×10^{-8} and 5×10^{-9} torr. In related application serial number 15/668,113, we disclosed a process flow that may be used to form a plurality of p-MTJ cells, and an encapsulation layer that electrically insulates adjacent p-MTJ cells.

In the exemplary embodiment depicted in FIG. 9, p-MTJ cells having top surface **18t** are formed in a circular shape such that width **b** in the x-axis direction is essentially equal to length **c** in the y-axis directions. However, in other embodiments, the p-MTJ cells may have an elliptical or a polygonal shape such that dimension **b** is unequal to **c**. Encapsulation layer **35** separates adjacent p-MTJ cells.

In an alternative embodiment shown in FIG. 2a, all of the p-MTJ layers are retained from the first embodiment in FIG. 1a. However, the stacking order yields p-MTJ **19** with sidewall **19s** and a top spin valve configuration wherein optional seed layer **11**, FL **17**, non-magnetic spacer **16**, SyAP pinned layer **15**, and capping layer **18** are sequentially formed on substrate **8**. FL magnetization **17m** is antiparallel to AP1 layer magnetization **14a** while the AP2 layer has magnetization **12m** aligned antiparallel to that of the AP1 layer. Note that all of the aforementioned magnetizations could be flipped 180° (not shown) to effectively provide the same AP state for p-MTJ **19** as shown in FIG. 2a.

During a write process that comprises switching current **I_{w3}**, the AP state in FIG. 2a is switched to the P state in FIG. 2b. Magnetizations **14a**, **12m** for the AP1 and AP2 layers, respectively, remain unchanged in the p-MTJ. However, FL magnetization **17a** is now aligned parallel to **14a** in the p-MTJ shown in FIG. 2b. Switching current **I_{w4}** may be applied to switch the P state of p-MTJ **10** in FIG. 2b to the AP state in FIG. 2a. Again, one or more p-MTJ cells in the memory array may be selectively switched from the P state to AP state, or vice versa during a write process.

In yet another embodiment of the present disclosure depicted in FIG. 3a, the p-MTJ in FIG. 1a is modified by adding a second non-magnetic spacer **26** on FL **17**, followed in order by a second SyAP pinned layer **25**, and an uppermost capping layer **18**. The second SyAP pinned layer has AP1 layer **24** contacting a top surface of the second non-magnetic spacer, a middle AFC layer **23**, and AP2 layer **22** on the middle AFC layer. Accordingly, a first spin valve structure **10-1** comprised of p-MTJ layers **11-17** is formed on substrate **8**, and a second spin valve structure **10-2** comprised of FL **17**, second spacer **26**, SyAP layer **25**, and capping layer **18** is formed on structure **10-1**. The double stack of layers is often referred to as a dual magnetic tunnel junction (DMTJ) **10-1/10-2**. Layers **25**, **26** may have the same composition as in layers **15**, **16**, respectively, that were described previously.

The DMTJ in FIG. 3a is said to have an AP/AP state since FL magnetization **17a** is aligned antiparallel to AP1 layer magnetizations **14m** in spin valve structure **10-1**, and is antiparallel to AP1 layer magnetization **24m** in the second spin valve structure **10-2**. AP2 layer **22** has magnetization **22a** that is antiparallel to that of AP1 layer **24**, and AP2 layer **12** has magnetization **12a** that is antiparallel to **14m**. FL magnetization **17a** may be switched to FL magnetization **17m** in FIG. 3b by employing switching current **I_{w5}** to produce a P/P state where FL magnetization is now parallel to both AP1 layer magnetizations **14m**, and **24m**. Similarly, the P/P state in one or more p-MTJ cells may be selectively switched to an AP/AP state by application of switching current **I_{w6}**.

As we described in related patent application HT17-038, the DMTJ configuration in FIGS. 3a-3b is a so-called non-working state for the purpose of lowering critical switching current (I_c) since the spin torque placed on the FL

from AP1 layer **14** effectively cancels that from AP1 layer **24** when the resistance x area (RA) product for spacer **16** is equal to the RA for spacer **26**. On the other hand, the DMTJ configuration depicted in FIGS. 3c-3d shows a so-called working state that substantially lowers (I_C) since the spin torque applied to FL **17** when conducting a current (**lw7** or **lw8**) through AP1 layer **14** adds to the spin torque on the FL from current through AP1 layer **24**. Thus, current **lw7** switches the DMTJ from a P/AP magnetic state in FIG. 3c to an AP magnetic state in FIG. 3d, and current **lw8** switches the AP/P magnetic state to a P/AP magnetic state. We also disclosed embodiments for substantially reducing the RA for first spacer **16** compared with the RA for second spacer **26** in order to generate an acceptable DRR for the DMTJ.

Referring to FIG. 4, it should be understood that p-MTJ cells are typically subjected to annealing processes and stray magnetic fields that cause the AP1 and AP2 layers, and FL to comprise multiple magnetic domains rather than the ideal situation of a single domain aligned in a perpendicular-to-plane direction. Thus, in addition to magnetization **17a** in FL **17**, there may be multiple FL domains wherein one or more domains has a magnetization **17x** comprising both of a horizontal and vertical component such that the net moment is not purely perpendicular-to-plane. It should be understood that magnetization **17a** representing an AP state may be replaced by magnetization **17m** represented a P state (not shown) for the p-MTJ cell. Likewise, one or more AP1 layer domains tends to have magnetization **14x** that has both of a horizontal and vertical component, and one or more AP2 layer domains has magnetization **12x** that has both of a horizontal and vertical component.

There may be one or more domains in each of the FL, AP1, and AP2 layers in which a magnetization is aligned opposite to the dominant perpendicular-to-plane direction, or purely in-plane. For example, AP2 layer is shown with at least one domain having magnetization **12m** that is opposite to magnetizations **12a**. We have found that multiple domains in one or more of the magnetic layers, and especially in the AP1 and AP2 layers, results in abnormal switching behavior. In other words, the "normal" write current necessary to switch a p-MTJ having a single magnetic domain in each of the magnetic layers from an AP state to a P state, or vice versa (FIGS. 1a-1b), is often insufficient to switch the FL when AP1 and AP2 layers have multiple domains as in FIG. 4. In certain

p-MTJ cells with a critical dimension of 100 nm or less, the failure (error) rate to switch FL magnetization may be in the range of 30 ppm to 100 ppm, which is unacceptable for MRAM or STT-MRAM to be competitive with other memory technologies.

According to initialization methods described herein, the switching error rate is substantially reduced to less than 10 ppm. A first embodiment of an initialization method of the present disclosure is depicted in FIG. 5 and comprises a step of applying a magnetic field **30** in the plane of the p-MTJ layers. As a result, FL magnetization **17h**, AP1 layer magnetization **14h**, and AP2 layer magnetization **12h** are each in the plane of their respective layers, and orthogonal to the z-axis direction. The in-plane magnetic field has a magnitude from about 1000 Oe to 30000 Oe, and is applied at a temperature proximate to room temperature, and in the absence of an applied electrical current. In some embodiments, the duration of the in-plane magnetic field is substantially less than 1 second. Although the in-plane magnetic field is applied during any portion of the p-MTJ fabrication process, the process is preferably performed after the final annealing process. In some embodiments, the final anneal may be performed after p-MTJ sidewall **10s** in FIG. 1a (or **19s** in FIG. 2a) is formed. In other embodiments, a final anneal is performed during or after an encapsulation layer is deposited to electrically insulate adjacent p-MTJ cells from one another. The duration of the initialization step may be a plurality of seconds, or as short as a plurality of milliseconds. Furthermore, the initialization process may be repeated one or more times after device fabrication is completed.

Referring to FIG. 6a, after the applied magnetic field **30** is removed, metal oxide/FM layer interface **40** between non-magnetic spacer **16** and AP1 layer **14** induces a single magnetic domain in the AP1 layer wherein magnetization **14m** in all regions of the AP1 layer is perpendicular-to-plane. Likewise, there is a metal oxide/FM layer interface **41** where the non-magnetic spacer adjoins FL **17**. Interface **41** induces a single magnetic domain in the FL in which FL magnetization **17m** in all FL regions is perpendicular-to-plane and in the same vertical direction as in the AP1 layer to give a P magnetic state for the p-MTJ. Note there is an equal probability that interface **41** induces a single FL domain (AP state) in which FL magnetization is aligned opposite to that shown in FIG.

6a. Because of an appropriate thickness of AFC layer **13**, AF coupling between the AP1 layer and AP2 layer **12** is maximized and a single domain occurs in the AP2 layer wherein magnetization **12a** in all AP2 regions is aligned in a vertical direction opposite to that in the AP1 layer. There is an equal probability that interface **40** induces AP1 layer magnetization **14a** (FIG. 6b), and as a result of AF coupling, AP2 layer magnetization **12m** is opposite to **14a**.

Although the effect of the initialization method is shown with respect to SyAP layer **15** in a bottom spin valve configuration, a single domain for each of the AP1 and AP2 layers is also formed within SyAP layer **15** in a top spin valve configuration, and within SyAP layers **15**, **25** in the dual spin valve structure described earlier with regard to FIGS. 3a-3b, and the DMTJ in FIGS. 3c-3d.

According to a second embodiment, the initialization method of the present disclosure comprises the application of a magnetic field in a perpendicular-to-plane direction to establish a single domain in each of the AP1 layer **14**, AP2 layer **12**, and FL **17**. For example, magnetic field **31** may be applied in a negative z-axis direction that is orthogonal to substrate top surface **8t**. As a result, all magnetizations including **17m** in the FL, **14m** in the AP1 layer, and **12m** in the AP2 layer are aligned parallel to the direction of the applied field. In an alternative embodiment (not shown), the applied field may be in a positive z-axis direction such that all magnetizations in the FL, AP1 and AP2 layers are temporarily aligned 180° opposite to **17m**, **14m**, and **12m**, respectively, in FIG. 7.

Referring to FIG. 8, magnetization **14a** in AP1 layer **14** aligns opposite to that of magnetization **12m** in AP2 layer **12** after the applied field is removed because of AF coupling through AFC layer **13** in SyAP pinned layer **15**, and because of interfacial perpendicular anisotropy induced by the metal oxide/magnetic layer interface **40**. According to a preferred embodiment, magnetization **12m** is designed to have a greater magnitude than that of magnetization **14a** in order to cancel stray fields on the free layer **17**. Thus, only magnetization **14m** in FIG. 7 reverses direction once the applied field **31** is removed. The AFC layer has an appropriate thickness to maximize AF coupling. For example, a preferred thickness is 4 Angstroms for an AFC layer made of Ru. Thus, magnetizations in each region of the AP1 and AP2 layers

are aligned in a perpendicular-to-plane direction such that each of the AP1 and AP2 layers effectively has a single magnetic domain.

In FIG. 9, a top-down view of a memory array comprised of p-MTJ **10** in FIGS. 1a-1b, p-MTJ **19** in FIGS. 2a-2b, or p-MTJ **10-2** in FIGS. 3a-3b is shown. In the exemplary embodiment each of the p-MTJ cells has a circular shape having a width **b** and length **c**, and is surrounded by encapsulation layer **35**. In other embodiments (not shown) each p-MTJ may have an elliptical or polygonal shape such that **b** is unequal to **c**.

Encapsulation layer **35** may be one of SiO_yN_z , AlO_yN_z , TiO_yN_z , SiC_yN_z , or MgO , or any combination of the aforementioned materials where $y + z > 0$. In alternative embodiments, the encapsulation layer may be a metal carbide, or another metal oxide, metal nitride, metal oxynitride, or metal carbonitride used in the art. Typically, the encapsulation layer is deposited on the substrate top surface to completely fill spaces between adjacent p-MTJ cells. Thereafter, a planarization method such as a chemical mechanical polish (CMP) process is employed to form an encapsulation layer top surface that is coplanar with p-MTJ top surface **18t**.

Following the planarization process to form the p-MTJ array in FIG. 9, a top electrode layer comprised of a plurality of parallel conductive lines (not shown) is formed by a conventional method on the plurality of MTJ cells. Accordingly, each p-MTJ is formed between a top conductive line and a bottom electrode (BE). During a write process with one of the switching currents I_{w1} - I_{w8} described previously, the switching current flows from a top conductive line to the BE, or in a reverse direction.

We have demonstrated the benefits of the initialization process of the present disclosure with results from an experiment where a plurality of circular p-MTJ cells where $b = c = 100$ nm (FIG. 9) was fabricated in an array on a 10 Mb MRAM chip. Each p-MTJ was formed with a bottom spin valve configuration represented by p-MTJ **10** in FIGS. 1a-1b. The p-MTJ cells with top surface **18t** were patterned with a conventional process flow including patterning a photoresist layer (not shown) on a top surface of a p-MTJ stack of layers, and transferring the pattern of circular islands through the p-MTJ stack with an etching process comprised of a plurality of reactive ion etch steps. The patterned p-MTJ cells were annealed with a temperature of 400°C for more

than 2 hours. Thereafter, encapsulation layer **35** comprised of SiOyNz was deposited and a CMP process was performed as described previously. Finally, a top electrode layer (not shown) was formed such that a conductive line contacted each p-MTJ top surface.

The current (I_P) for the P state and current (I_{AP}) of the AP state were measured for 5120 p-MTJ normal cells and error bits. Results are shown in FIG. 10 where the difference ($I_P - I_{AP}$) is plotted as a function of I_P . Ideally, the results from all p-MTJ cells should fall proximate to line **50** and within a region proximate to oval **42**. However, in addition to the so-called normal p-MTJs in the aforementioned region, we observed a considerable number of “abnormal” p-MTJs in a region **40** substantially below line **50**, and a smaller number of abnormal p-MTJs in region **41** at higher I_P values than p-MTJs in region **40**.

We have determined that the root cause of abnormal p-MTJs in region **40** is multiple domains in AP1 and AP2 layers in the SyAP pinned layer. In other words, the switching current for switching the free layer from a P to AP state, or vice versa, in a normal p-MTJ is not sufficient for switching the free layer in an abnormal p-MTJ. Since a key objective of advanced MRAM and STT-MRAM designs is lower power consumption, the higher switching current for abnormal p-MTJs is not acceptable when competing with other technologies such as static random access memory (SRAM). Moreover, higher switching current places more stress on the non-magnetic spacer (i.e. tunnel barrier layer) that leads to shorter device lifetime.

According to an embodiment of the present disclosure, the same array of p-MTJ cells that produced the results depicted in FIG. 10 were subjected to an initialization method comprised of an applied vertical field of 20000 Oe for hundreds of milliseconds. After removal of the applied field, I_P and I_{AP} were measured again for the 5120 p-MTJ normal cells and error bits. Results are provided in FIG. 11 and show essentially all abnormal p-MTJ cells in region **40** prior to initialization have been corrected to now have I_{AP} and I_P that falls within the range of a normal cell in region **42**. Abnormal p-MTJs with data points in region **41** are attributed to a defective tunnel barrier layer, and are not corrected to a normal cell by the application of an applied field according to an embodiment described herein. Thus, uniformity in switching current is

significantly improved for a plurality of p-MTJ cells on the MRAM chip by employing an initialization method of the present disclosure.

In summary, we have observed that a typical switching error rate in the range of 30 ppm to 100 ppm for p-MTJ cells that have not been initialized is reduced significantly to less than 10 ppm when the p-MTJ cells are subjected to an initialization process according to an embodiment of the present disclosure. Furthermore, the initialization process may be repeated one or more times after device fabrication to offset the effect of stray fields or temperature excursions that may cause a recurrence of multiple domains in the free layer and pinned layer.

While this disclosure has been particularly shown and described with reference to, the preferred embodiment thereof, it will be understood by those skilled in the art that various changes in form and details may be made without departing from the spirit and scope of this disclosure.

We claim:

1. An initialization process for providing a single domain in a free layer (FL), and in AP1 and AP2 layers within a synthetic antiparallel (SyAP) pinned layer in a perpendicular magnetic tunnel junction (p-MTJ) cell, comprising:

(a) providing a p-MTJ cell on a substrate wherein the p-MTJ cell comprises a SyAP pinned layer having an antiferromagnetic (AF) coupling layer between an AP1 layer and an AP2 layer, a FL, and a tunnel barrier layer that forms a first interface with the AP1 layer and a second interface with the FL;

(b) applying a magnetic field in an in-plane direction such that all magnetizations in each of the FL, AP1 layer, and AP2 layer are aligned in the direction of the applied magnetic field; and

(c) removing the applied magnetic field to yield a single magnetic domain in each of the FL, AP1 and AP2 layers, comprising:

(1) magnetization in all regions of the AP1 layer aligned in a first perpendicular-to-plane (vertical) direction as a result of interfacial perpendicular magnetic anisotropy (PMA) at the first interface;

(2) magnetization in all regions of the FL aligned in the first vertical direction or opposite to the first vertical direction as a result of interfacial PMA at the second interface; and

(3) magnetization in all regions of the AP2 layer in a second vertical direction opposite to the first vertical direction as a result of AF coupling with the AP1 layer through the AF coupling layer.

2. The initialization process of claim 1 wherein the in-plane magnetic field is applied at a temperature proximate to room temperature, and in the absence of an applied electrical current.

3. The initialization process of claim 1 wherein the in-plane magnetic field is applied for a duration of substantially less than 1 second.

4. The initialization process of claim 1 wherein the p-MTJ has a bottom spin valve configuration, top spin valve configuration, or a dual spin valve configuration.

5. The initialization process of claim 1 wherein the AF coupling layer is Ru that has a thickness of 4, 9, or 14 Angstroms in order to maximize AF coupling between the AP1 and AP2 layers.

6. The initialization process of claim 1 wherein the in-plane magnetic field is applied after a final annealing step is performed during fabrication of the p-MTJ cell.

7. The initialization process of claim 1 wherein the p-MTJ cell is formed during fabrication of a magnetic random access memory (MRAM) device, spin-torque transfer (STT)-MRAM, or a spintronic device that is a spin torque oscillator (STO), sensor, or biosensor.

8. The initialization process of claim 1 wherein the strength of the applied magnetic field is from about 1000 Oe to 30000 Oe.

9. The initialization process of claim 1 wherein the in-plane magnetic field is applied after an encapsulation layer is deposited to electrically insulate the p-MTJ cell from adjacent p-MTJ cells.

10. The initialization process of claim 1 wherein the in-plane magnetic field is applied a plurality of times during fabrication of the p-MTJ cell.

11. An initialization process for providing a single domain in a free layer (FL), and in AP1 and AP2 layers within a synthetic antiparallel (SyAP) pinned layer in a perpendicular magnetic tunnel junction (p-MTJ) cell, comprising:

(a) providing a p-MTJ cell on a substrate wherein the p-MTJ cell comprises a SyAP pinned layer having an antiferromagnetic (AF) coupling layer between an AP1 layer and an AP2 layer, a FL, and a tunnel barrier layer that forms a first interface with the AP1 layer and a second interface with the FL;

(b) applying a magnetic field in a first perpendicular-to-plane (vertical) direction such that all magnetizations in each of the FL, AP1 layer, and AP2 layer are aligned in the first vertical direction; and

(c) removing the applied magnetic field to yield a single magnetic domain in each of the FL, AP1 and AP2 layers, comprising:

(1) magnetization in all regions of the AP2 layer aligned in the first vertical direction;

(2) magnetization in all regions of the FL aligned in the first vertical direction or opposite to the first vertical direction as a result of interfacial PMA at the second interface; and

(3) magnetization in all regions of the AP1 layer in a second vertical direction opposite to the first vertical direction as a result of AF coupling

with the AP2 layer through the AF coupling layer, and as a result of interfacial perpendicular magnetic anisotropy (PMA) at the first interface.

12. The initialization process of claim **11** wherein the vertical magnetic field is applied at a temperature proximate to room temperature, and in the absence of an applied electrical current.

13. The initialization process of claim **11** wherein the vertical magnetic field is applied for a duration of substantially less than 1 second.

14. The initialization process of claim **11** wherein the p-MTJ has a bottom spin valve configuration, top spin valve configuration, or a dual spin valve configuration.

15. The initialization process of claim **11** wherein the AF coupling layer is Ru that has a thickness of 4, 9, or 14 Angstroms in order to maximize AF coupling between the AP1 and AP2 layers.

16. The initialization process of claim **11** wherein the vertical magnetic field is applied after a final annealing step is performed during fabrication of the p-MTJ cell.

17. The initialization process of claim **11** wherein the p-MTJ cell is formed during fabrication of a magnetic random access memory (MRAM) device, spin-torque transfer (STT)-MRAM, or a spintronic device that is a spin torque oscillator (STO) or biosensor.

18. The initialization process of claim **11** wherein the strength of the applied vertical magnetic field is from about 1000 Oe to 30000 Oe.

19. The initialization process of claim **11** wherein the vertical magnetic field is applied after an encapsulation layer is deposited to electrically insulate the p-MTJ cell from adjacent p-MTJ cells.

20. The initialization process of claim **11** wherein the vertical magnetic field is applied a plurality of times during fabrication of the p-MTJ cell.

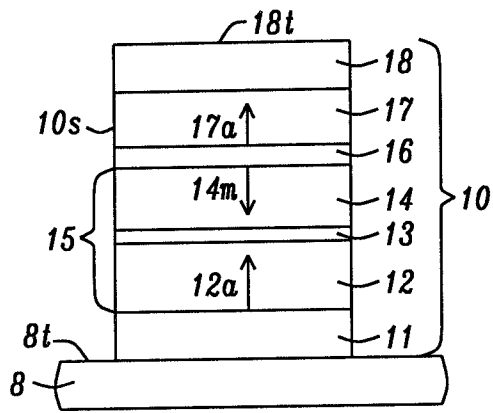


FIG. 1a

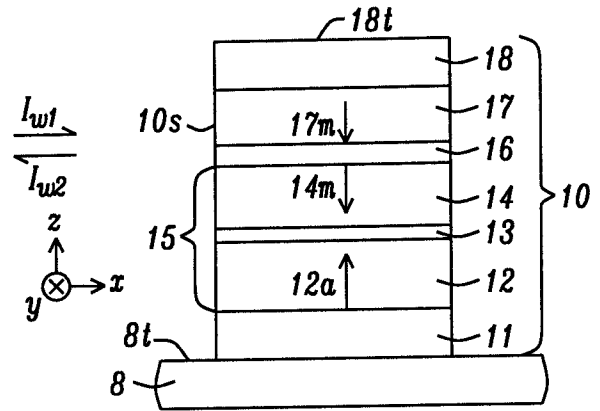


FIG. 1b

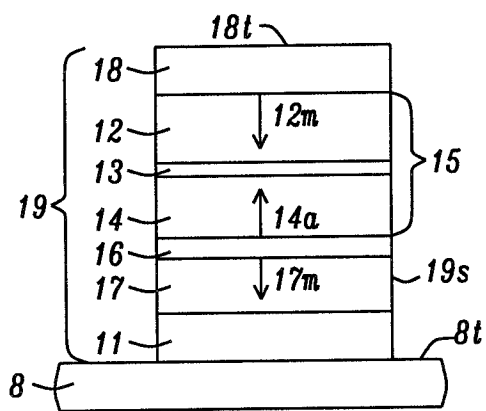


FIG. 2a

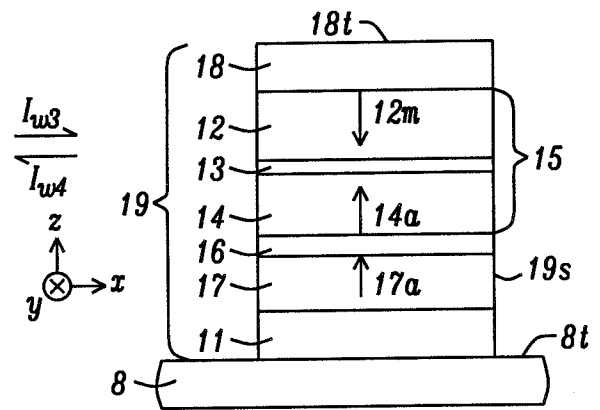


FIG. 2b

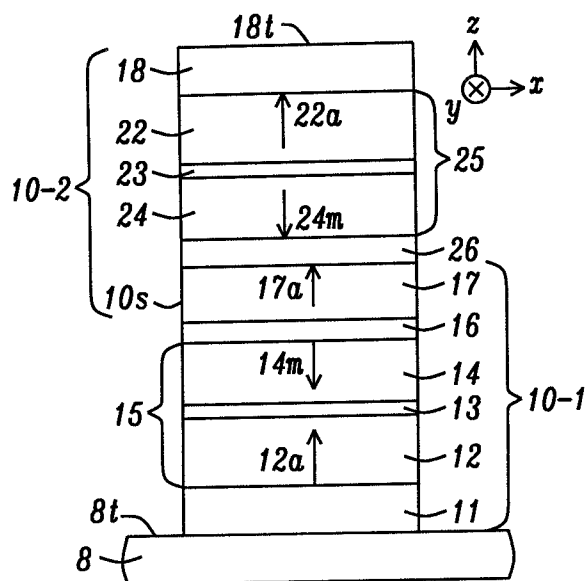


FIG. 3a

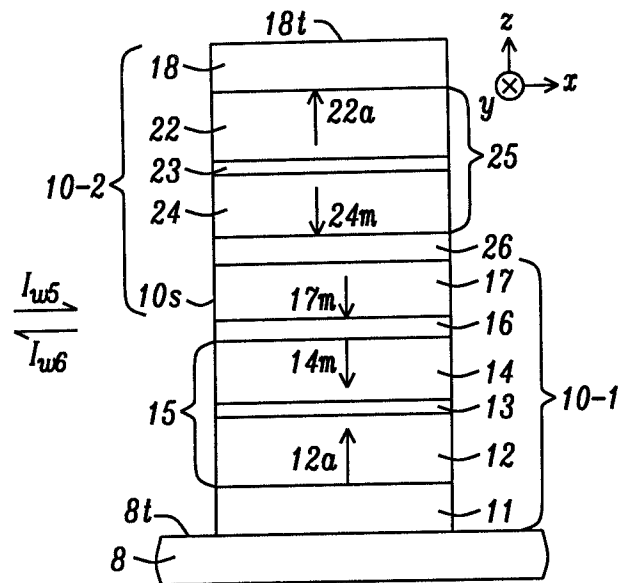


FIG. 3b

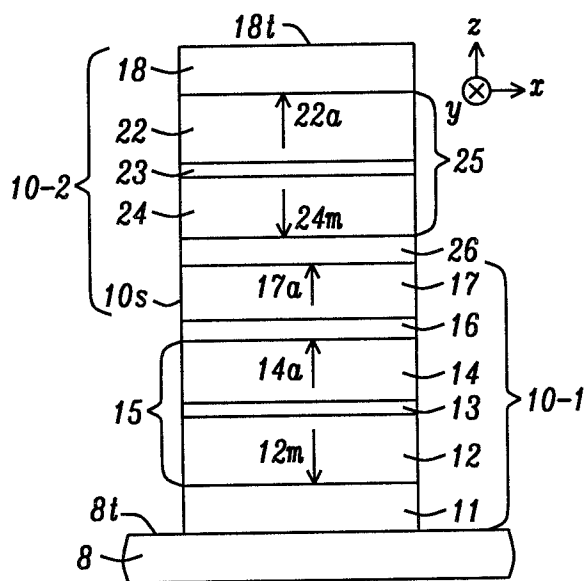


FIG. 3c

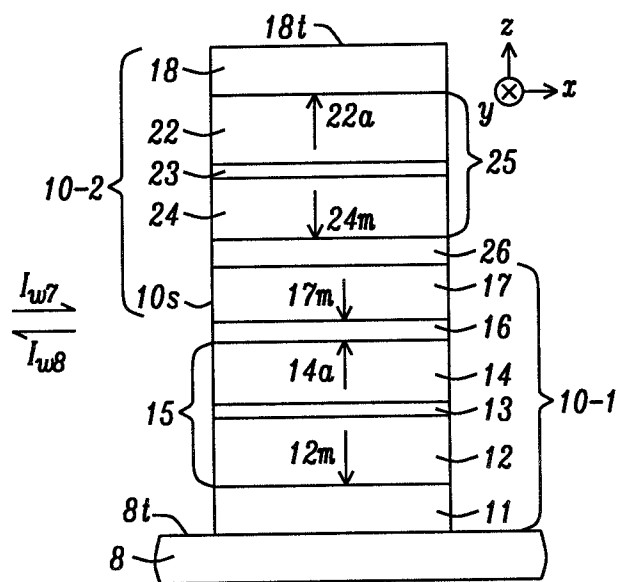


FIG. 3d

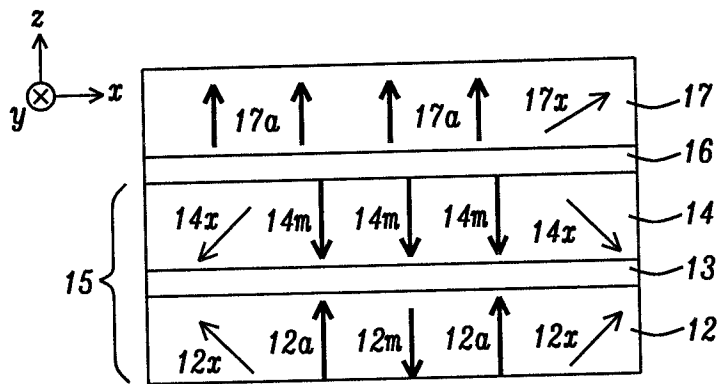


FIG. 4

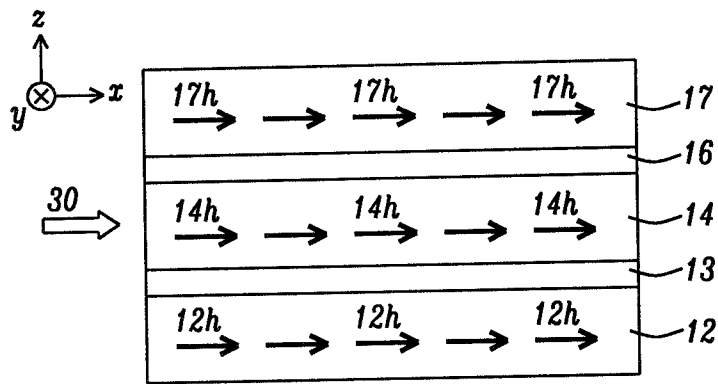


FIG. 5

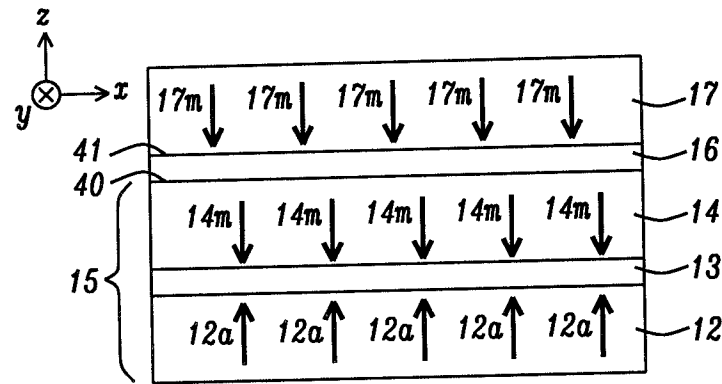


FIG. 6a

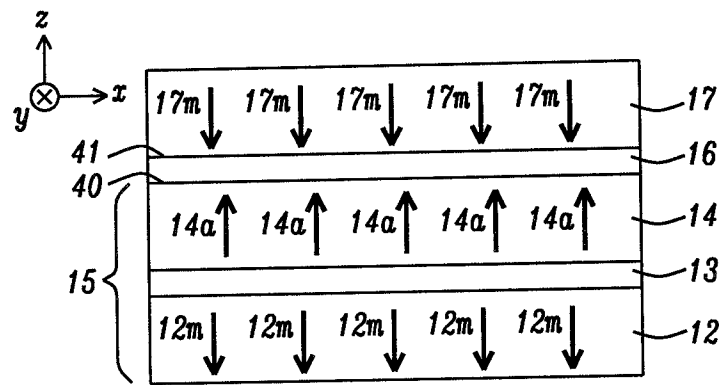


FIG. 6b

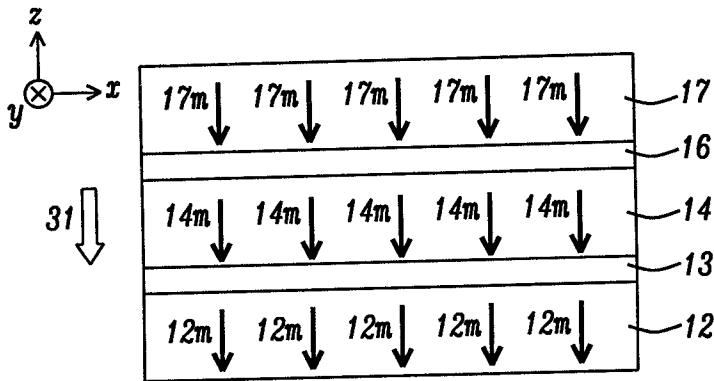


FIG. 7

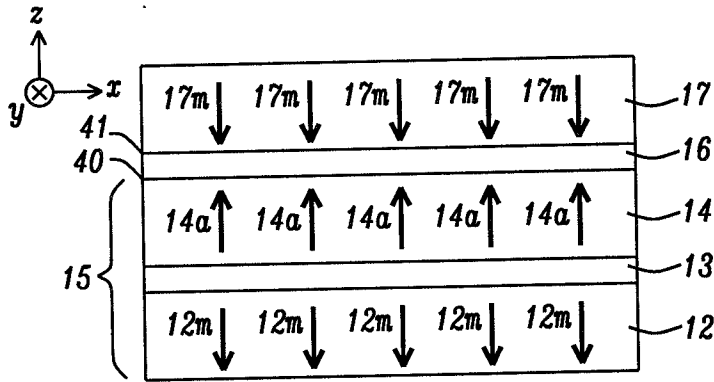


FIG. 8

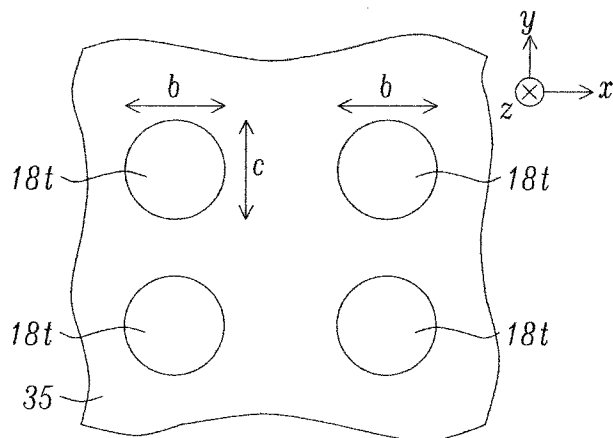


FIG. 9

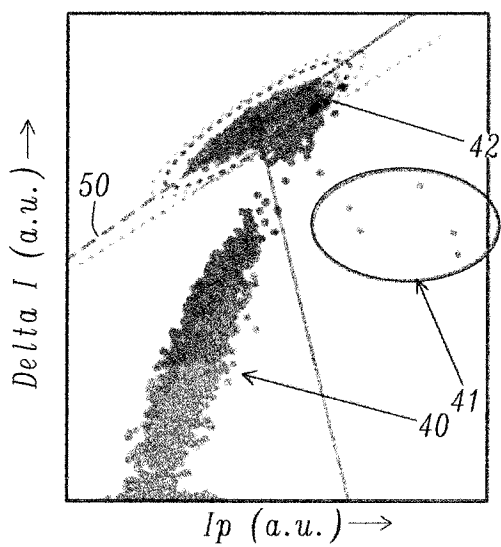


FIG. 10

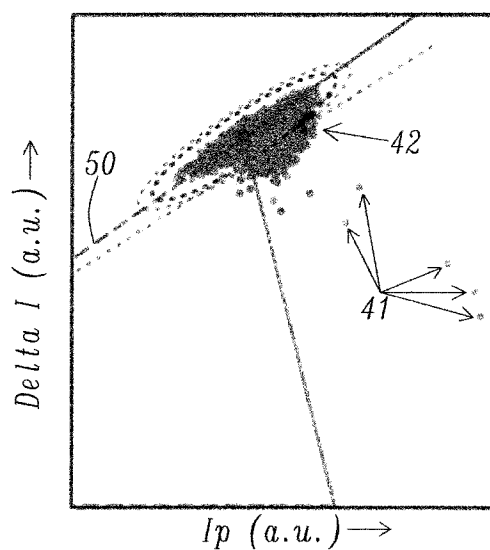


FIG. 11

INTERNATIONAL SEARCH REPORT

International application No
PCT/US2018/059803

A. CLASSIFICATION OF SUBJECT MATTER
INV. G11C11/16
ADD.

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
G11C

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

EPO-Internal, COMPENDEX, INSPEC, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2015/071430 A1 (ZHU XIAOCHUN [US] ET AL) 12 March 2015 (2015-03-12) paragraph [0038]; figure 7 paragraph [0039] - paragraph [0043]; figures 8-9	1-20
X	US 2013/155754 A1 (APALKOV DMYTRO [US] ET AL) 20 June 2013 (2013-06-20)	11-20
A	paragraph [0036] - paragraph [0041]; figure 3 paragraph [0059] - paragraph [0064]; figures 14-15	1-10
A	US 9 337 415 B1 (OH SANGMUN [US] ET AL) 10 May 2016 (2016-05-10) column 2, line 41 - column 3, line 64; figure 2	1-20
	-/--	



Further documents are listed in the continuation of Box C.



See patent family annex.

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"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

6 February 2019

Date of mailing of the international search report

13/02/2019

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Authorized officer

Lecoutre, Renaud

INTERNATIONAL SEARCH REPORT

International application No
PCT/US2018/059803

C(Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	US 2010/065935 A1 (HORNG CHENG T [US] ET AL) 18 March 2010 (2010-03-18) paragraph [0035] - paragraph [0041]; figure 2 -----	1-20

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No

PCT/US2018/059803

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
US 2015071430 A1	12-03-2015	US 2015071430 A1	12-03-2015
		WO 2015035043 A1	12-03-2015
US 2013155754 A1	20-06-2013	KR 20130071404 A	28-06-2013
		US 2013155754 A1	20-06-2013
US 9337415 B1	10-05-2016	CN 105990517 A	05-10-2016
		DE 102016003130 A1	22-09-2016
		FR 3033936 A1	23-09-2016
		GB 2537039 A	05-10-2016
		JP 6202764 B2	27-09-2017
		JP 2016178301 A	06-10-2016
		KR 20160113048 A	28-09-2016
		US 9337415 B1	10-05-2016
US 2010065935 A1	18-03-2010	NONE	